

G2304

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BV _{DSS}	25V
R _{DS(ON)}	117mΩ
I _D	2.7A

Description

The G2304 provides the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

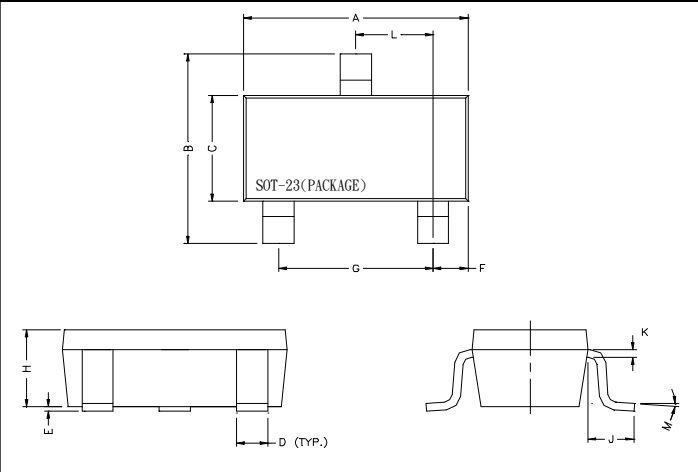
Features

- Super High Dense Cell Design for Extremely Low R_{DS(ON)}
- Reliable and Rugged

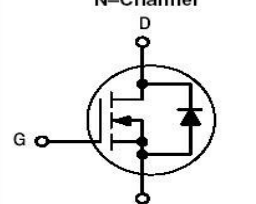
Applications

- Power Management in Notebook Computer
- Portable Equipment
- Battery Powered System.

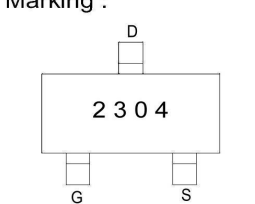
Package Dimensions



N-Channel



Marking :



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	1.90	REF.
B	2.40	2.80	H	1.00	1.30
C	1.40	1.60	K	0.10	0.20
D	0.35	0.50	J	0.40	-
E	0	0.10	L	0.85	1.15
F	0.45	0.55	M	0'	10'

Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	25	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ³ , V _{GS} @4.5V	I _D @TA=25°C	2.7	A
Continuous Drain Current ³ , V _{GS} @4.5V	I _D @TA=70°C	2.2	A
Pulsed Drain Current ^{1,2}	I _{DM}	10	A
Power Dissipation	P _D @TA=25°C	1.38	W
Linear Derating Factor		0.01	W/°C
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 ~ +150	°C

Thermal Data

Parameter	Symbol	Ratings	Unit
Thermal Resistance Junction-ambient ³ Max.	R _{thj-a}	90	°C/W

Electrical Characteristics(Tj = 25°C Unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV_{DSS}	25	-	-	V	$V_{GS}=0, I_D=250\mu A$
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_j$	-	0.1	-	V/°C	Reference to 25°C, $I_D=1mA$
Gate Threshold Voltage	$V_{GS(th)}$	1.0	-	3.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Forward Transconductance	g_{fs}	-	3.4	-	S	$V_{DS}=4.5V, I_D=2.5A$
Gate-Source Leakage Current	I_{GSS}	-	-	±100	nA	$V_{GS}= \pm 20V$
Drain-Source Leakage Current(Tj=25°C)	I_{DSS}	-	-	1	uA	$V_{DS}=25V, V_{GS}=0$
Drain-Source Leakage Current(Tj=70°C)		-	-	10	uA	$V_{DS}=25V, V_{GS}=0$
Static Drain-Source On-Resistance ²	$R_{DS(on)}$	-	-	117	mΩ	$I_D=2.5A, V_{GS}=10V$
		-	-	190		$I_D=2.0A, V_{GS}=4.5V$
Total Gate Charge ²	Q_g	-	5.9	10	nC	$I_D=2.5A$
Gate-Source Charge	Q_{gs}	-	0.8	-		$V_{DS}=15V$
Gate-Drain ("Miller") Change	Q_{gd}	-	2.1	-		$V_{GS}=10V$
Turn-on Delay Time ²	$T_{d(on)}$	-	4.5	-	ns	$V_{DS}=15V$ $I_D=1A$ $V_{GS}=10V$ $R_G=6\Omega$ $R_D=15\Omega$
Rise Time	T_r	-	11.5	-		
Turn-off Delay Time	$T_{d(off)}$	-	12	-		
Fall Time	T_f	-	3	-		
Input Capacitance	C_{iss}	-	110	-	pF	$V_{GS}=0V$ $V_{DS}=15V$ $f=1.0MHz$
Output Capacitance	C_{oss}	-	85	-		
Reverse Transfer Capacitance	C_{rss}	-	39	-		

Source-Drain Diode

Forward On Voltage ²	V_{SD}	-	-	1.2	V	$I_S=1.25A, V_{GS}=0 T_j=25^\circ C$
Continuous Source Current(Body Diode)	I_S	-	-	1	A	$V_D=V_G=0V, V_S=1.2V$
Pulsed Source Current (Body Diode) ¹	I_{SM}	-	-	10	A	

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width ≤ 300us, duty cycle ≤ 2%.

3. Surface mounted on 1 in² copper pad of FR4 board;270°C/w when mounted on min. copper pad.

Characteristics Curve

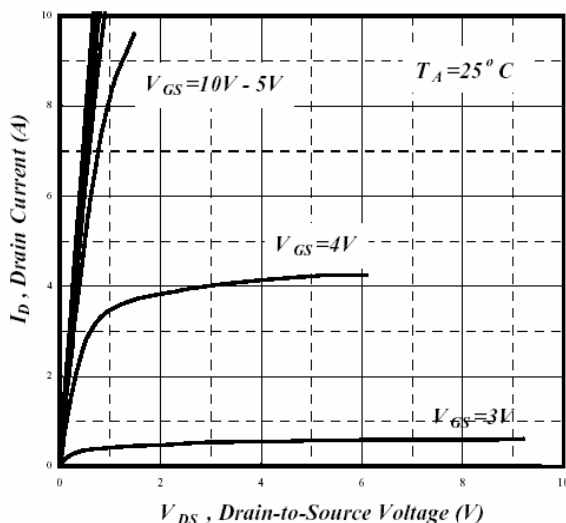


Fig 1. Typical Output Characteristics

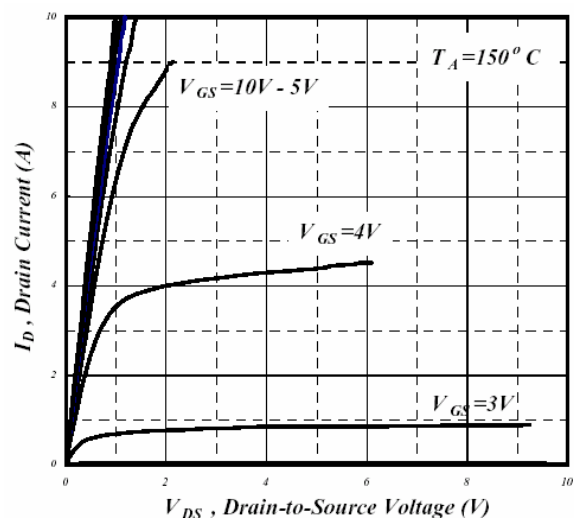


Fig 2. Typical Output Characteristics

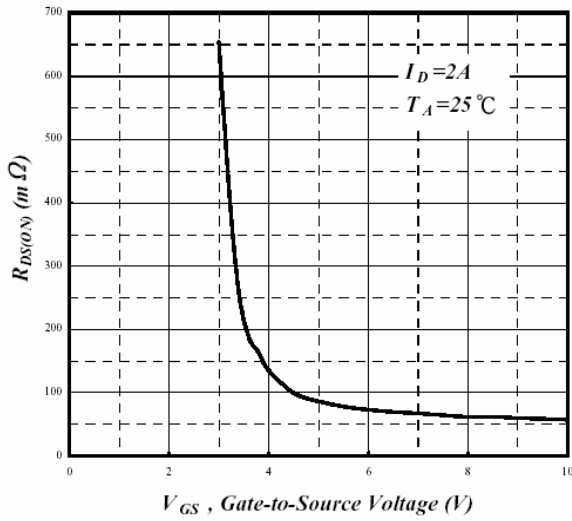


Fig 3. On-Resistance v.s. Gate Voltage

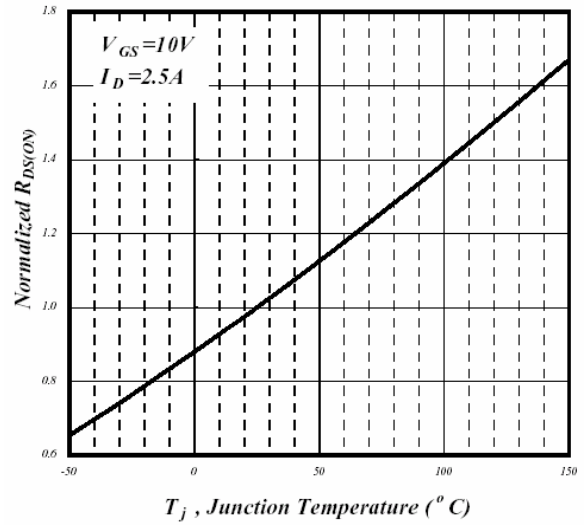


Fig 4. Normalized On-Resistance v.s. Junction Temperature

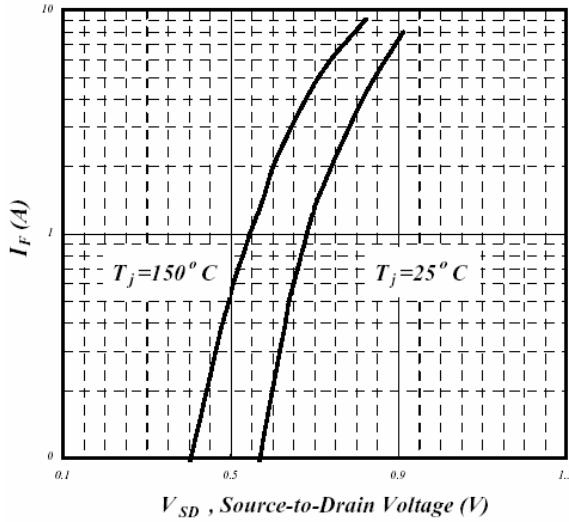


Fig 5. Forward Characteristic of Reverse Diode

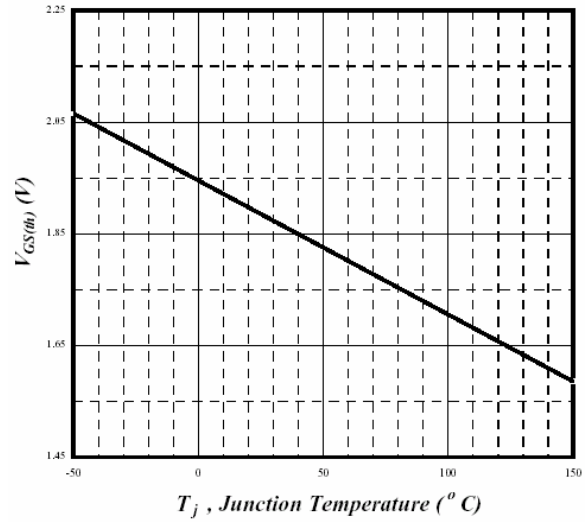


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

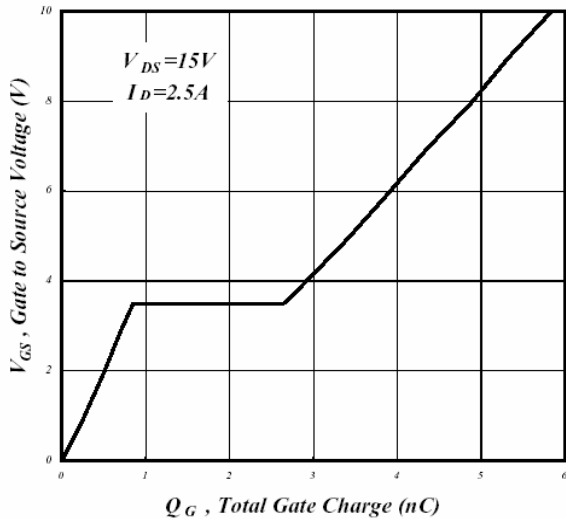


Fig7. Gate Charge Characteristics

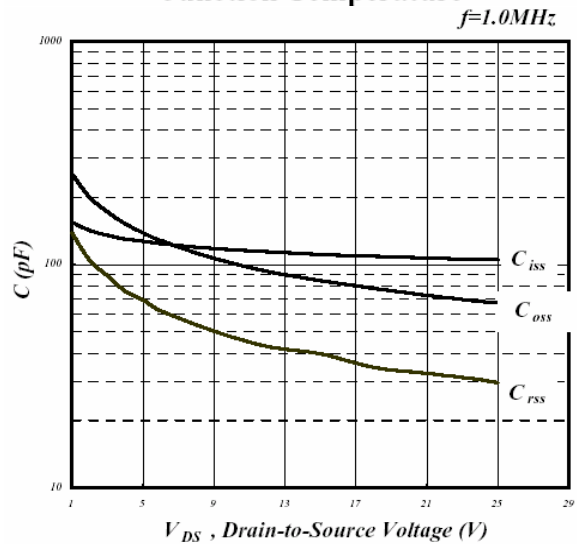


Fig 8. Typical Capacitance Characteristics

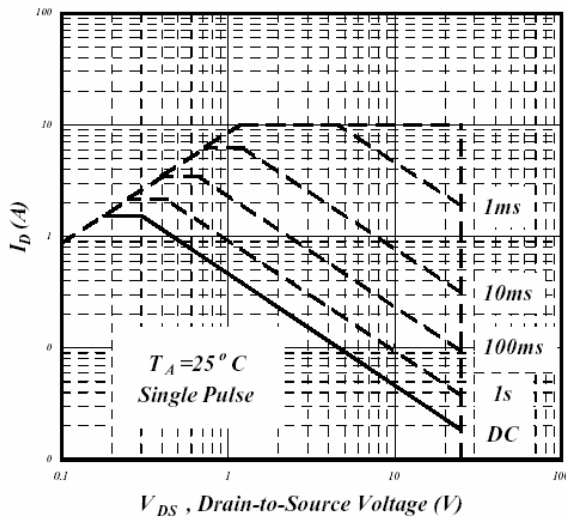


Fig 9. Maximum Safe Operating Area

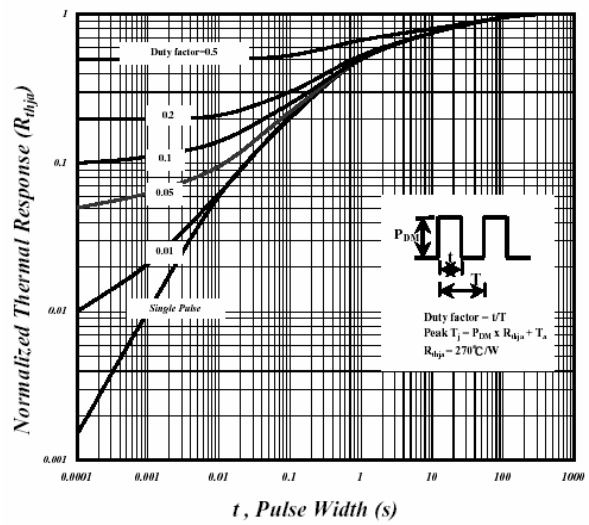


Fig10. Effective Transient Thermal Impedance

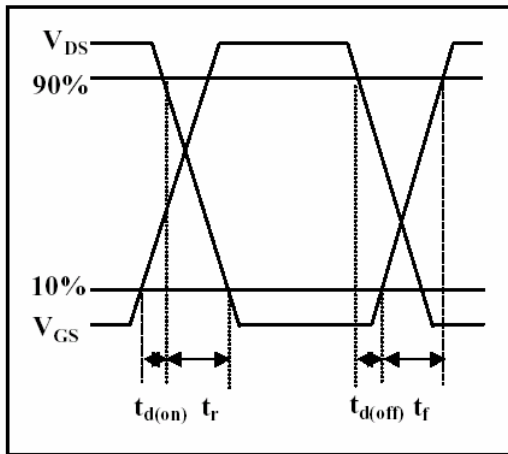


Fig 11. Switching Time Waveform

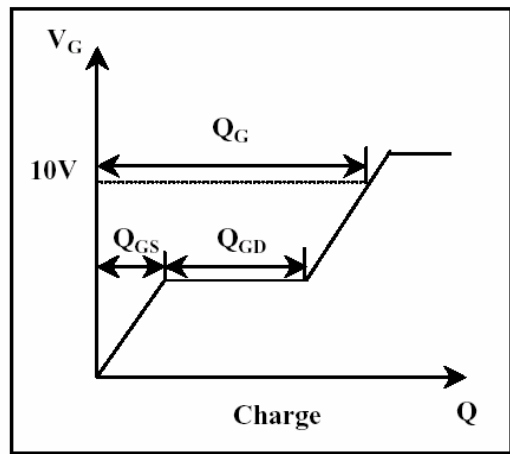


Fig 12. Gate Charge Waveform

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Head Office And Factory:

- **Taiwan:** No. 17-1 Tatung Rd. Fu Kou Hsin-Chu Industrial Park, Hsin-Chu, Taiwan, R. O. C.
- TEL : 886-3-597-7061 FAX : 886-3-597-9220, 597-0785
- **China:** (201203) No.255, Jang-Jiang Tsai-Lueng RD. , Pu-Dung-Hsin District, Shang-Hai City, China
- TEL : 86-21-5895-7671 ~ 4 FAX : 86-21-38950165